2SC5939

Silicon NPN epitaxial planar type

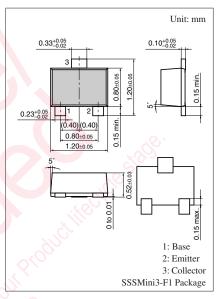
For high-frequency amplification/oscillation/mixing

Features

- \bullet High transition frequency $f_{\rm T}$
- Small collector output capacitance (Common base, input open circuited) C_{ob} and reverse transfer capacitance (Common base) C_{rb}
- SSS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Symbol	Rating	Unit	
V _{CBO}	15	V	
V _{CEO}	10	V	
V _{EBO}	3	v	
I _C	50	mA	
P _C	100	mW	
Tj	125	°C	
T _{stg}	-55 to +125	°C	
	V _{CBO} V _{CEO} V _{EBO} I _C P _C T _j	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	



Marking Symbol: 1S

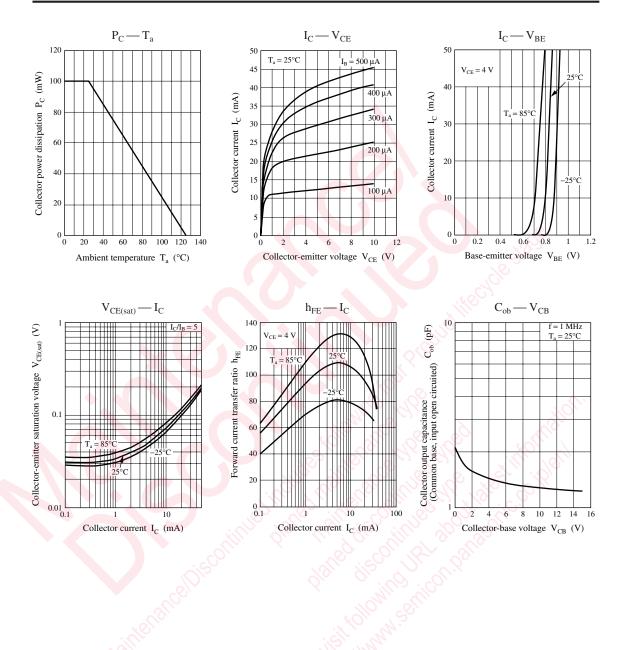
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	10			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, I_{\rm C} = 0$	3	S		V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$	3		1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 4 V, I_C = 5 mA$	75		400	
h _{FE} ratio	Δh_{FE}	$V_{CE} = 4 V, I_C = 100 \mu A$	0.75		1.6	
		$V_{CE} = 4 V, I_C = 5 mA$				
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 20 \text{ mA}, I_{\rm B} = 4 \text{ mA}$			0.5	V
Transition frequency	f _T	$V_{CE} = 4 \text{ V}, I_E = -5 \text{ mA}, f = 200 \text{ MHz}$	1.4	1.9	2.7	GHz
Collector output capacitance	C _{ob}	$V_{CB} = 4 V, I_E = 0, f = 1 MHz$		1.4		pF
(Common base, input open circuited)		all and With				
Reverse transfer capacitance	C _{rb}	$V_{CB} = 4 V, I_E = 0, f = 1 MHz$		0.45		pF
(Common base)						
Collector-base parameter	r _{bb} ' • C _C	$V_{CB} = 4 V, I_E = -5 mA, f = 31.9 MHz$		11		ps

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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